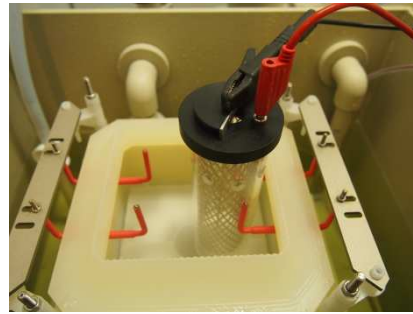




Stress analysing tube

Layer stress can be analysed using the stress analysing tube. The metal strips are plated on opposite sides and bend outwards due to layer stress. The stress can be analysed qualitatively and quantitatively.

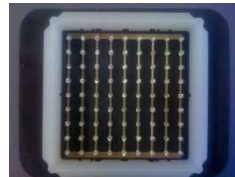


Illumination for suncup[®] integration

For illumination assisted processes, light tubes are installed from two sides of the suncup[®], which has corresponding transparent opening in the sidewalls. The light tubes are equipped with high power LED. Depending on the power, water cooling can be integrated.

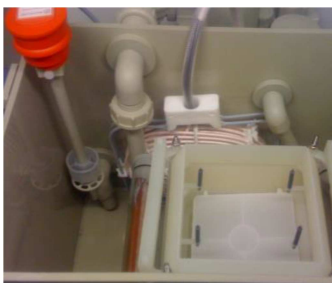


Another option is the integration of a light matrix into the crown, which is available in different wafer sizes



Heating

Different heating options can be integrated. When heating is installed, low volume level safety features are included.



Wafer Rotation

A computer controlled wafer rotation unit with a screw-less wafer clamping offers additional process parameters, e.g. for optimising layer thickness uniformity.



Electrical backside contact

As the backside of the wafer keeps dry, backside contacting can be applied and handling is simple using vacuum pincette or our backside contact chuck with screw-less clamping.



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